TX7-705C-C-ST3

STRATUM III SMD TCXO CMOS



Features

- Applications: transmission, TDM networks, SDH, SONET, wireless communications, IEEE 1588v2, SyncE, STRATUM III, wireless backhaul, metro carrier Ethernet, femtocells, picocells
- Holdover stability: ±0.37 ppm over 24 h
- Overall stability: ±4.60 ppm including 20 years aging
- Output signal: CMOS
- Compatible to the DFA S2 (Fordahl SA)

Parameter	Specification	
Frequency range	9.83040 ~ 32.0 MHz	
Standard frequencies	10.0, 12.80, 16.3840, 19.440, 20.0, 25.0, 26.0 & 32.0 MHz	
Frequency stability:	≤ ±4.60 ppm	overall stability including 20 years aging
vs. temperature	≤ ±0.28 ppm	-40 ~ +85 °C
vs. aging	≤ ±3.0 ppm	20 years
Holdover stability (1)	≤ ±0.37 ppm	over 24 hours
Frequency tolerance ex. factory	≤ ±0.50 ppm	@ +25 °C
Supply voltage	+3.3 V or +5.0 V	±5 %
Supply current	< 6 mA	
Output signal	CMOS	
Output load	15 pF	±5 %
Phase noise @ 12.8 MHz carrier frequency	-145 dBc/Hz	@ 10 kHz
Operating temperature range	0 ~ +70 °C	indoor use
	-40 ~ +85 °C	outdoor use
Storage temperature range	-55 ~ +125 °C	
Packaging units	tape & reel tape only	500 or 1'000 pieces < 500 pieces

⁽¹⁾ Including: frequency stability, vs temperature, supply change of ±5 % and aging over 24 hours

Pin function

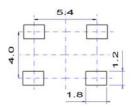
1 not connected

5 GND

6 Output

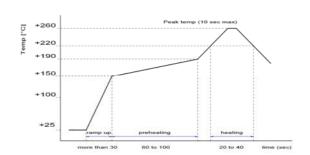
10 Vdc

Example for solder pattern



All other pins are not connected

Do not design any conductive path between the pattern Example for IR reflow soldering temperature



2002/95/EC RoHS compliant

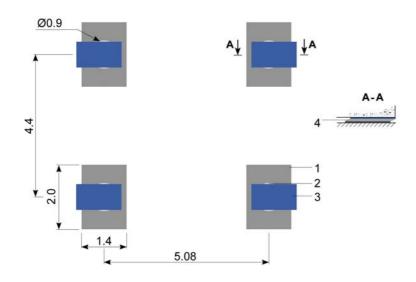


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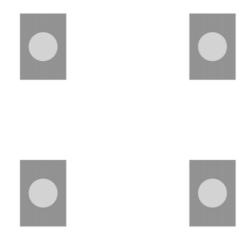


Accuracy of fit of the pinning of TX7-705-C (QuartzCom AG) on the footprint recommended for DFA S2 (Fordahl SA) in comparison with the DFA S2 pinning fit



- 1: DFA S2 footprint
- 2. DFA S2 pin
- 3. TX7-705-C pin
- 4. Solder

DFA S2 footprint with DFA S2 pin



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